2020-2-27 Rev.2.0

RD Number: RD110

RD Title: TB67S158FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1	Check terminal	–	–	Check pin		
2	VCOM_AB	0	Check terminal	–	–	Check pin		✓
3	VCOM_CD	0	Check terminal	–	–	Check pin		✓
4	VDD	1	Check terminal	–	–	Check pin		
5	GND	6	Check terminal	–	–	Check pin		
6	DMODE1_CD	1	Check terminal	–	–	Check pin		
7	DMODE2_CD	1	Check terminal	–	–	Check pin		
8	DMODE1_AB	1	Check terminal	–	–	Check pin		
9	DMODE2_AB	1	Check terminal	–	–	Check pin		
10	CW/CCW_AB	1	Check terminal	–	–	Check pin		
11	RESET_AB	1	Check terminal	–	–	Check pin		
12	ENABLE_AB	1	Check terminal	–	–	Check pin		
13	CLK_AB	1	Check terminal	–	–	Check pin		
14	MODE0	1	Check terminal	–	–	Check pin		
15	MODE1	1	Check terminal	–	–	Check pin		
16	CW/CCW_CD	1	Check terminal	–	–	Check pin		
17	CLK_CD	1	Check terminal	–	–	Check pin		
18	ENABLE_CD	1	Check terminal	–	–	Check pin		
19	RESET_CD	1	Check terminal	–	–	Check pin		
20	ERR	1	Check terminal	–	–	Check pin		
21	OUTA+	1	Check terminal	–	–	Check pin		
22	OUTA-	1	Check terminal	–	–	Check pin		
23	OUTB+	1	Check terminal	–	–	Check pin		
24	OUTB-	1	Check terminal	–	–	Check pin		
25	OUTC+	1	Check terminal	–	–	Check pin		
26	OUTC-	1	Check terminal	–	–	Check pin		

27	OUTD+	1	Check terminal	–	–	Check pin		
28	OUTD-	1	Check terminal	–	–	Check pin		
29	ZD1	1	CMZ36	CMZ36	TOSHIBA	Zener diode	M-FLAT	
30	ZD2	1	CMZ36	CMZ36	TOSHIBA	Zener diode	M-FLAT	
31	R1	1	10kΩ 0.25W	–	–	Resistor		
32		2	Socket pin	–	–	Socket pin		
33	R2	1	10kΩ 0.25W	–	–	Resistor		
34		2	Socket pin	–	–	Socket pin		
35	C3	1	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	
36	C4	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
37	C5	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
38	C6	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
39	C7	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
40	C8	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
41	C9	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
42	C10	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
43	C11	0	0.1μF 100V	–	–	Chip capacitor	3.2mm×1.6mm	✓
44	C1	1	100μF 100V	–	–	Electrolytic capacitor		
45	C2	1	10μF 25V	–	–	Electrolytic capacitor		
46	SW1	1	Pin header 3P	–	–	Jumper		
47	(DEMODE1_CD)	1	Jumper socket	–	–	Jumper Short		
48	SW2	1	Pin header 3P	–	–	Jumper		
49	(DEMODE2_CD)	1	Jumper socket	–	–	Jumper Short		
50	SW3	1	Pin header 3P	–	–	Jumper		
51	(DEMODE1_AB)	1	Jumper socket	–	–	Jumper Short		
52	SW4	1	Pin header 3P	–	–	Jumper		
53	(DEMODE2_AB)	1	Jumper socket	–	–	Jumper Short		
54	SW5	1	Pin header 3P	–	–	Jumper		
55	(CW/CCW_AB)	1	Jumper socket	–	–	Jumper Short		
56	SW6	1	Pin header 3P	–	–	Jumper		
57	(RESET_AB)	1	Jumper socket	–	–	Jumper Short		
58	SW7	1	Pin header 3P	–	–	Jumper		
59	(ENABLE_AB)	1	Jumper socket	–	–	Jumper Short		
60	SW8	1	Pin header 3P	–	–	Jumper		

61	(CLK_AB)	1	Jumper socket	–	–	Jumper Short	
62	SW9	1	Pin header 3P	–	–	Jumper	
63	(MODE0)	1	Jumper socket	–	–	Jumper Short	
64	SW10	1	Pin header 3P	–	–	Jumper	
65	(MODE1)	1	Jumper socket	–	–	Jumper Short	
66	SW11	1	Pin header 3P	–	–	Jumper	
67	(CW/CCW_CD)	1	Jumper socket	–	–	Jumper Short	
68	SW12	1	Pin header 3P	–	–	Jumper	
69	(CLK_CD)	1	Jumper socket	–	–	Jumper Short	
70	SW13	1	Pin header 3P	–	–	Jumper	
71	(ENABLE_CD)	1	Jumper socket	–	–	Jumper Short	
72	SW14	1	Pin header 3P	–	–	Jumper	
73	(RESET_CD)	1	Jumper socket	–	–	Jumper Short	
74	CON1	1	Terminal block 2P	–	–	Terminal block 2P	
75		1	Terminal block 2P	–	–	Terminal block 2P	
76	CON2	1	Terminal block 2P	–	–	Terminal block 2P	
77		1	Terminal block 2P	–	–	Terminal block 2P	
78	IC1	1	TB67S158FTG	TB67S158FTG	TOSHIBA	Motor driver IC	QFN48	

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